

Abstract of the Disclosure

A chip thermistor is produced by first preparing green sheets containing a NTC thermistor ceramic material and an organic binder, then applying a resistor paste on one or
5 more of these green sheets and an inner electrode paste on some others, and forming a layered structure free of PTC materials by stacking and compressing together specified numbers of these green sheets. The layered structure is then subjected to a firing process and outer electrodes are formed on oppositely facing pair of outer end surfaces of the layered structure. The chip thermistor thus produced has a main body of a thermistor ceramic
10 material having a specified resistance-temperature characteristic, a pair of outer electrodes on its end surfaces, at least one resistor having resistance greater than 1Ω , and at least one pair of inner electrodes opposite each other and separated from each other with the thermistor ceramic material in between. The resistor and the pair of inner electrodes are connected in series or in parallel between the pair of outer electrodes.